REMARKS

The Office Action of March 23, 2007 was received and reviewed. Reconsideration and withdrawal of the currently pending rejections are requested for the reasons advanced in detail below.

In the Office Action mailed March 23, 2007, the Examiner states that claims 1-5 are pending and further rejects claims 1-5 as outlined therein. However, the Office Action, mailed March 23, 2007, is responsive to the Response to Notice of Non-Compliant Amendment, filed on January 24, 2007, which additionally includes newly added claims 6-12. Claims 6-12 of the instant application were never been examined and hence, Applicant respectfully requests full examination on the merits of these claims. Accordingly, Applicant further requests that the finality of the currently pending Office Action also be withdrawn.

Claims 1-5 were rejected under 35 U.S.C. §102(e) as being anticipated by U.S. Patent Application Publication No. US 2004/0224433 A1 to Yamazaki et al. Yamazaki et al., however, fails to render the claimed invention unpatentable. Each of the claims recite a specific combination of features that distinguishes the invention from the prior art in different ways. For example, independent claims 1 recites a combination that includes, among other things:

> forming a wiring by etching the conductive film with the resist pattern as a mask at an atmospheric pressure or a pressure close to the atmospheric pressure by using a first plasma generating device comprising a plurality of pairs of electrodes . . . forming an insulating film over the wiring . . . forming a contact hole by etching the insulating film at the atmospheric pressure or a pressure close to the atmospheric pressure by using a second plasma generating device provided with a pair of electrodes.

Independent claim 4 recites yet another combination that includes, inter alia,

> after forming the conductive film, forming a wiring by etching an unnecessary portion of the conductive film locally at an atmospheric pressure or a pressure close to the atmospheric pressure by using a first plasma

> generating device comprising a plurality of pairs of electrodes . . . forming an insulating film over the wiring . . . forming a contact hole by etching the insulating film at the atmospheric pressure or a pressure close to the atmospheric pressure by using a second plasma generating device provided with a pair of electrodes.

Additionally, independent claim 5 recites another combination that includes, for example,

> after forming the resist pattern, forming a wiring by etching an unnecessary portion of the conductive film locally at an atmospheric pressure or a pressure close to the atmospheric pressure by using a second plasma generating device comprising a plurality of pairs of electrodes . . . forming an insulating film over the wiring . . . forming a contact hole by etching the insulating film at the atmospheric pressure or a pressure close to the atmospheric pressure by using a second plasma generating device provided with a pair of electrodes.

At the very least, Yamazaki et al. fails to disclose or suggest any of these exemplary features recited in the independent claims 1 and 4-5. For example, Yamazaki et al. discloses a technique to manufacture a display device including applying a means to form a pattern such as a contact holed formed in a semiconductor film. Thus, while the method of Yamazaki et al. utilizes a pair of electrodes, Yamazaki et al. does not teach a manufacturing method of a display device including, *inter alia*, "forming a contact hole . . . by using a second plasma generating device provided with a pair of electrodes" as recited by claims 1 and 4-5.

For anticipation under 35 U.S.C. § 102, the reference must teach every aspect of the claimed invention either explicitly or impliedly. Any feature not directly taught must be inherently present (M.P.E.P. 706.02). Since each and every element, as set forth in the claims are not found either expressly or inherently described as required by the M.P.E.P., Yamazaki et al. cannot be said to anticipate the invention as claimed. Hence, withdrawal of the rejection is respectfully requested.

The remaining dependent claims depend from one of claims 1, 4 and 5 and are

therefore allowable at least for the above reasons and further for the additional features recited therein. Support for newly added claims 13-14 is found, at least, on page 18, lines 19-25; claims 15-17 are supported, at least, in FIG. 7B; claims 18-20 are supported, at least, on page 20, lines 22-26.

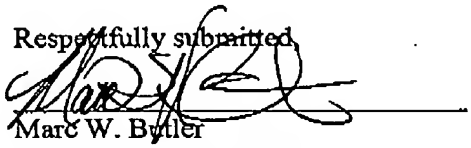
In addition, each of the dependent claims also recite combinations that are separately patentable.

In view of the foregoing remarks, this claimed invention, as amended, is not rendered obvious in view of the prior art references cited against this application. Applicant therefore request the entry of this response, the Examiner's reconsideration and reexamination of the application, and the timely allowance of the pending claims.

In discussing the specification, claims, and drawings in this response, it is to be understood that Applicant in no way intends to limit the scope of the claims to any exemplary embodiments described in the specification and/or shown in the drawings. Rather, Applicant is entitled to have the claims interpreted broadly, to the maximum extent permitted by statue, regulation, and applicable case law.

Should the Examiner believe that a telephone conference would expedite issuance of the application, the Examiner is respectfully invited to telephone the undersigned patent agent at (202) 585-8316.

Respectfully submitted,



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